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ABSTRACT

An integrated device package may include a glass interposer having one or more conductive vias extending through the glass interposer from a top side of the glass interposer to a bottom side of the glass interposer, the bottom side of the glass interposer comprising one or more contact pads. The device package may include an integrated device die mounted and electrically connected to the top side of the glass interposer. The device package may also include an encapsulating material disposed over at least a side surface of the glass interposer, a portion of the top surface of the glass interposer, and a side surface of the integrated device die.

